**Printed circuit board material with high workability - contains insulation board composed of layer made with polyphenylene oxide resin compsn. contg. crosslinkable polymer and/or monomer**

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| JP 63224940 | A | 19880920 | JP 8759719 | A | 19870315 | 198843 | B |
| JP 93064586 | B | 19930914 | JP 8759719 | A | 19870315 | 199339 | |

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Abstract (Basic): JP 63224940 A

Printed circuit board contains an insulation board which is composed of a layer made with a polyphenylene oxide resin compsn. contg. a polyphenylene oxide, a crosslinkable polymer and/or a crosslinkable monomer, and an inorganic filler, and a layer of a base material impregnated with a resin but not the polyphenylene oxide resin compsn.

Polyphenylene oxide is pref. poly (2,6-dimethyl-1,4-phenylene oxide), etc. Crosslinkable polymer is 1,2-polybutadiene, styrene-butadiene copolymer, etc. Crosslinkable monomer is tri-allycyanurate and/or triallyisocyanurate, etc. Inorganic filler is Al oxide, SiO2, TiO2, etc. Base material is cloth of glass, aramid, polyester, etc. Resin for impregnation is epoxy resin, polyimide resin, etc.

USE/ADVANTAGE - The material is useful for printed-circuit boards applicable in UHF and SHF bands. The printed-circuit board is superior in permittivity (i.e., 10.8 (1M Hz) in contrast to 9.8 using copper clad alumina insulation base board), and workability for drilling, etc.

Title Terms: PRINT; CIRCUIT; BOARD; MATERIAL; HIGH; WORK; CONTAIN; INSULATE ; BOARD; COMPOSE; LAYER; MADE; POLYPHENYLENE; OXIDE; RESIN; COMPOSITION; CONTAIN; CROSSLINK; POLYMER; MONOMER
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